Customer Information Notification

201811039I

Issue Date: 05-Dec-2018
Effective Date: 06-Dec-2018

Management Summary

Final test platform expansion for trim of the MMA845x and SX845x family within NXP Kuala Lumpur, Malaysia site.

Change Category

☐ Wafer Fab Process	☐ Assembly Process	☐ Product Marking	☐ Test Location	☐ Design
☐ Wafer Fab Materials	☐ Assembly Materials	☐ Mechanical Specification	☑ Test Process	☐ Errata
☐ Wafer Fab Location	☐ Assembly Location	☐ Packing/Shipping/Labeling	☑ Test Equipment	☐ Electrical spec./Test coverage
☐ Firmware	☐ Other			

MMA845x and SX845x Family Final Test Platform Expansion

Description

NXP Semiconductors announces the final test platform expansion for trim of the MMA845x and SX845x family within the NXP Kuala Lumpur, Malaysia site.

Reason

The test platform expansion is a NXP business decision to assure supply of the MMA845x and SX845x family.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist direct

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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